Application

- Motor drive
- · Inverter, Converter
- · Photovoltaics, wind power generation.
- · Induction heating equipment.

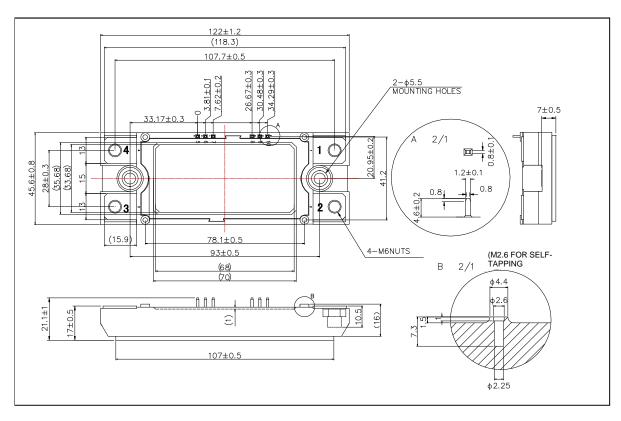
Features

- 1) Low surge, low switching loss.
- 2) High-speed switching possible.
- 3) Reduced temperature dependence.

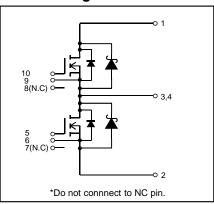
Construction

This product is a half bridge module consisting of SiC-DMOS and SiC SBD from ROHM.

•Dimensions & Pin layout (Unit : mm)



Circuit diagram



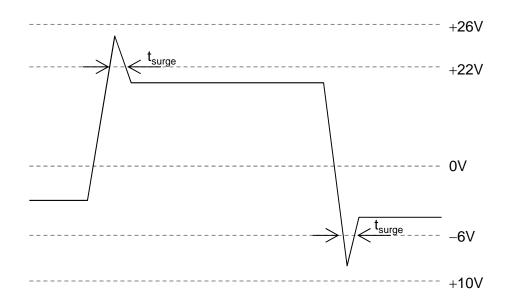
		, ,			
Parameter	Symbol	Conditions	Limit	Unit	
Drain-source voltage	V_{DSS}	G-S short	1200		
Gate-source voltage(+)	V _{GSS}	D-S short	22	V	
Gate-source voltage(-)			-6		
G - S voltage (t _{surge} <300ns)	V _{GSSsurge}	D-S short	-10 to 26]	
Drain current *1	I _D	$DC(T_c=60^{\circ}C)$	80		
Drain current	I _{DRM}	Pulse (T _c =60°C) 1ms * ²	160		
Source current *1	I _S	$DC(T_c = 60^{\circ}C) V_{GS} = 18V$	80	A	
Source current	I _{SRM}	Pulse (T _c =60°C) 1ms V _{GS} =18V	160		
Total power disspation *3	Ptot	T _c =25°C	600	W	
Max junction temperature	T _{jmax}		175		
Junction temperature	T _{jop}		-40 to150	°C	
Storage temperature	T _{stg}		-40 to125		
Isolation voltage	Visol	Terminals to baseplate, f=60Hz AC 1min.	2500	Vrms	
Mounting torque		Main Terminals : M6 screw	4.5	N·m	
Mounting torque	_	Mounting to heat shink : M5 screw	3.5		

•Absolute maximum ratings (Tj = 25°C)

(*1) Case temperature (T_c) is defined on the surface of base plate just under the chips.

(*2) Repetition rate should be kept within the range where temperature rise if die should not exceed T_{jmax} . (*3) T_j is less than 175°C

Example of acceptable Vgs waveform



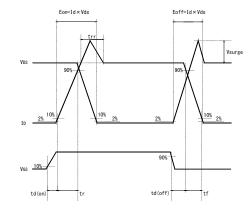
•Electrical characteristics (Tj=25°C)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
On state static	V _{DS(on)}		T _i =25°C	_	2.8	3.5	V
On-state static		I _D =80A, V _{GS} =18V	T _i =125°C	-	4.2	_	
Drain-Source Voltage			T _j =150°C	_	4.8	5.5	
Drain cutoff current	I _{DSS}	V _{DS} =1200V, V _{GS} =0V	_	_	1.2	mA	
	V _{SD}	V _{GS} =0V, I _S =80A	T _j =25°C		1.7	2.0	V
			T _j =125°C	-	2.1	_	
Source-drain voltage			T _j =150°C	-	2.3	3.3	
Source-drain voltage			T _j =25°C		1.4	_	
		V _{GS} =18V, I _S =80A	T _j =125°C		1.7	_	
			T _j =150°C		1.8	_	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =10V, I _D =13.2mA	1.6		4	V	
Gate-source leak current	I _{GSS}	V_{GS} =22V, V_{DS} =0V	_	—	0.5	μΑ	
	GSS	V_{GS} = -6V, V_{DS} =0V	-0.5	—	—		
	t _{d(on)}	V _{GS(on)} =18V, V _{GS(off)} =0V	_	20	—		
	t_r V _{DS} =600V			—	30	_	l
Switching characteristics	t _{rr}	I _D =80A	_	35	_	ns	
	t _{d(off)}	R _G =0.82Ω	_	80	_		
	t _f	inductive load		40	_		
Input capacitance	Ciss	V _{DS} =10V, V _{GS} =0V, f=1N	_	8	_	nF	
Gate Registance	R _{Gint}	T _j =25°C		3.0	_	Ω	
Stray Inductance	Ls			25	_	nH	
Creepage distance	_	Terminal to heat sink		11.5	_	mm	
		Terminal to terminal			19.0	_	mm
Clearance distance	_	Terminal to heat sink			9.5	_	mm
		Terminal to terminal			13.0	_	mm
Junction-to-case thermal		DMOSFET (1/2 module) * ⁴		_	—	0.25	°C/W
resistance		SBD (1/2 module) *4		1	0.32		
Case-to-heat sink	R _{th} (c-f)	Case to heat sink, per 1	_	0.035			
Thermal resistance	rt _{th} (C-I)	Thermal grease applied			—		

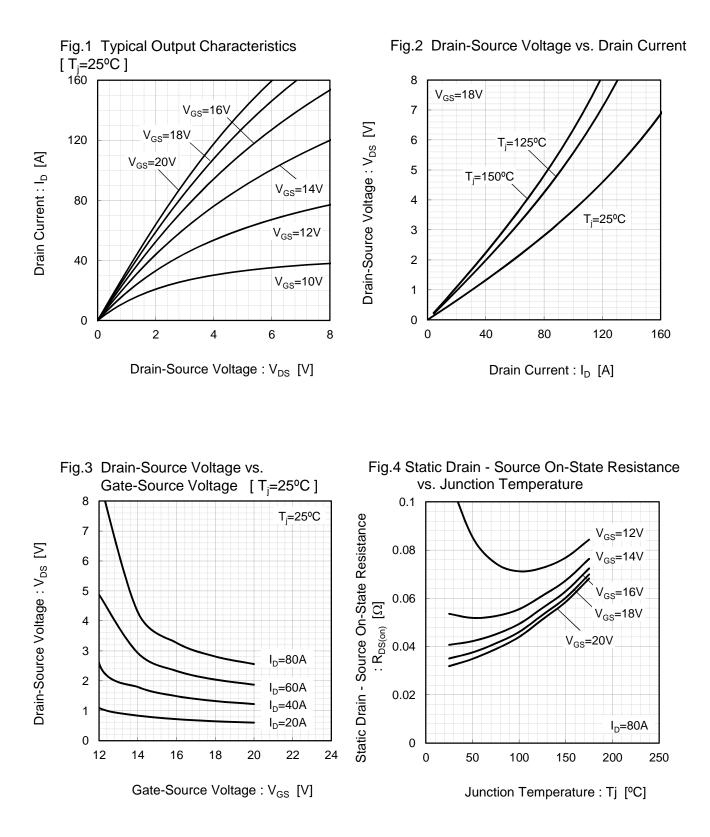
(*4) Measurement of Tc is to be done at the point just under the chip.

- (*5) Typical value is measured by using thermally conductive grease of λ =0.9W/(m · K).
- (*6) SiC devices have lower short cuicuit withstand capability due to high current density. Please be advised to pay careful attention to short cuicuit accident and try to adjust protection time to shutdown them as short as possible.
- (*7) If the Product is used beyond absolute maximum ratings defined in the Specifications, as its internal structure may be dameged, please replace such Product with a new one.

<Wavelength for Switching Test>







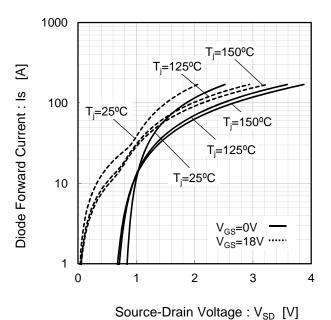
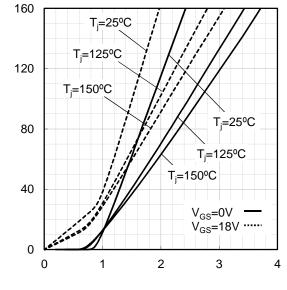


Fig.5 Forward characteristic of Diode

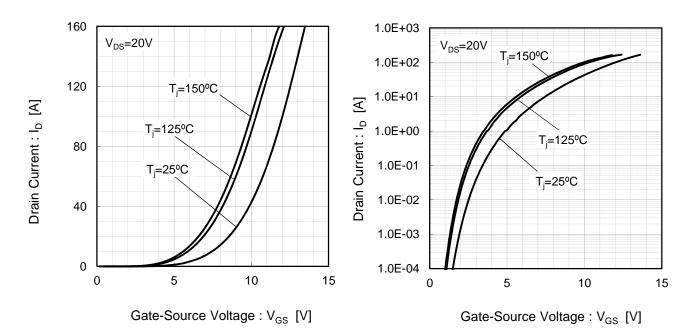
Fig.6 Forward characteristic of Diode



Source-Drain Voltage : V_{SD} [V]

Fig.7 Drain Current vs. Gate-Source Voltage

Fig.8 Drain Current vs. Gate-Source Voltage



Diode Forward Current : Is [A]

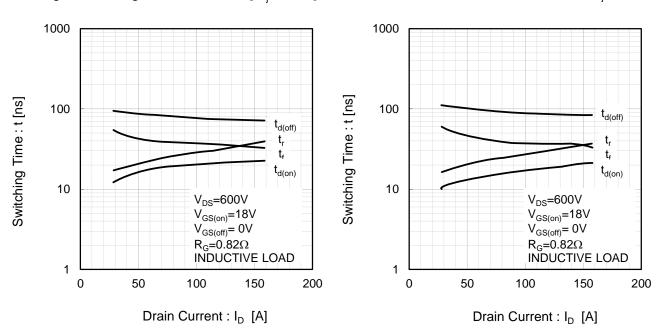
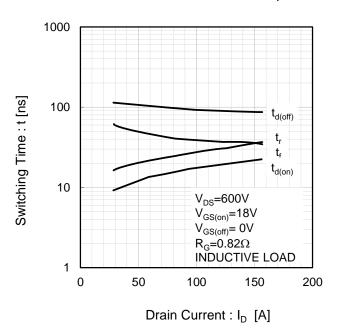
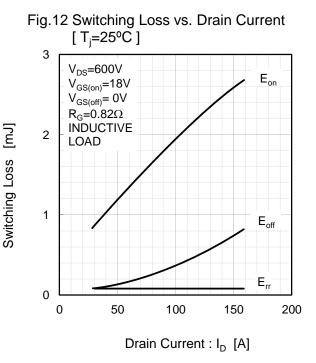


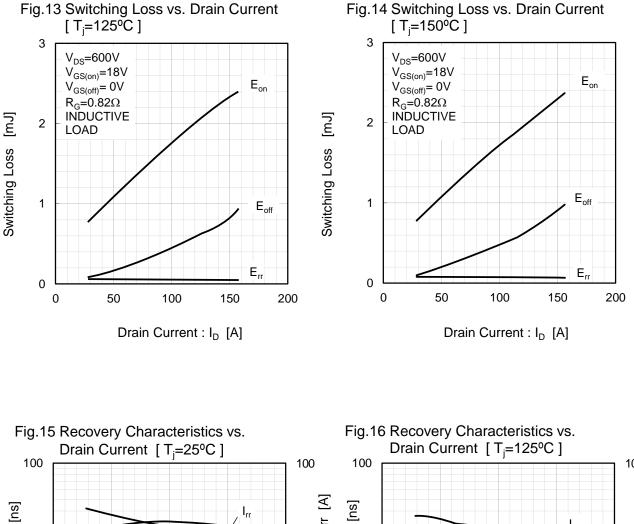
Fig.9 Switching Characteristics [T_i=25°C]

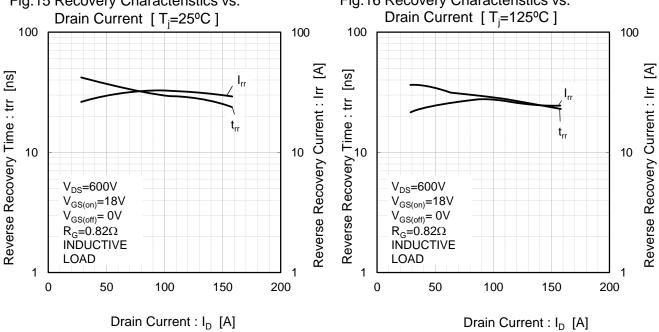
Fig.10 Switching Characteristics [T_i=125°C]

Fig.11 Switching Characteristics [T_i=150°C]









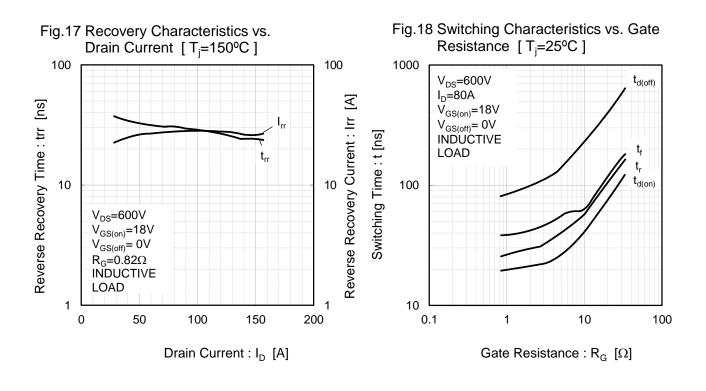
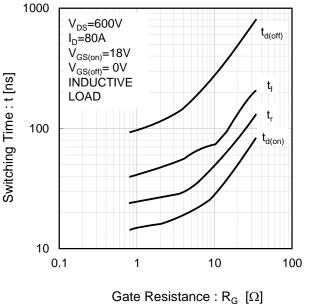
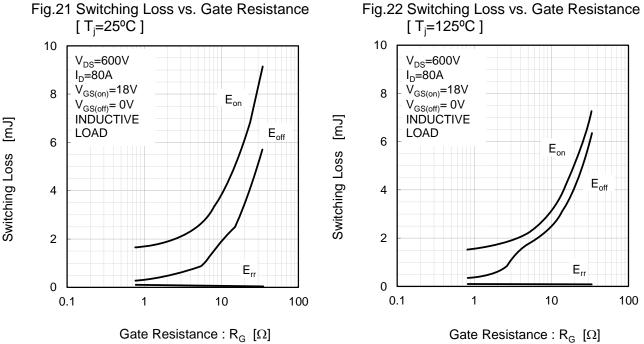
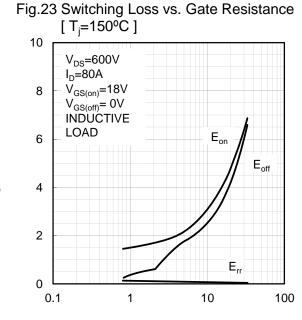


Fig.19 Switching Characteristics vs. Gate Resistance [T_i=125°C] 1000 V_{DS}=600V t_{d(off)} I_D=80A V_{GS(on)}=18V V_{GS(off)}= 0V INDUCTIVE Switching Time : t [ns] LOAD 100 t_{d(on)} 10 0.1 1 10 100 Gate Resistance : R_G [Ω]

Fig.20 Switching Characteristics vs. Gate Resistance [T_j=150°C]





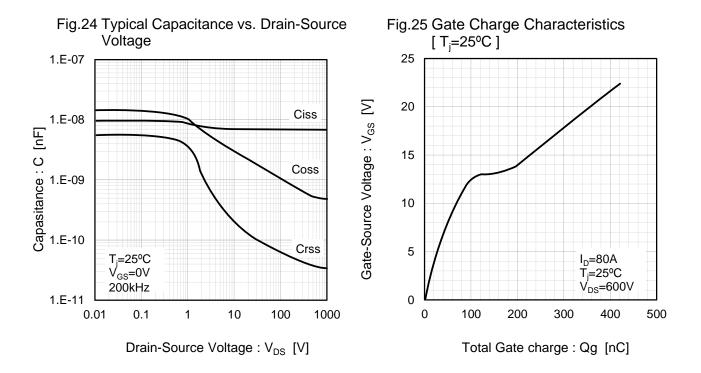


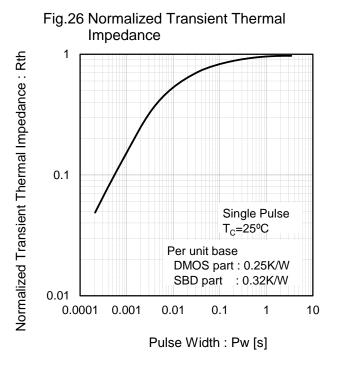
Gate Resistance : R_G [Ω]

Switching Loss [mJ]

Fig.22 Switching Loss vs. Gate Resistance









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